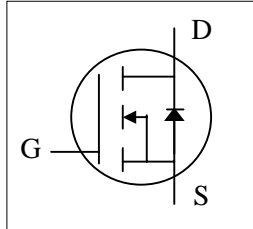




- ▼ Simple Drive Requirement
- ▼ Low Gate Charge
- ▼ Fast Switching

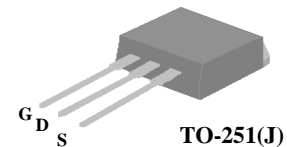
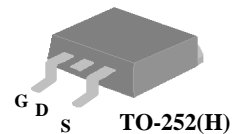


| | |
|--------------|--------------|
| BV_{DSS} | 30V |
| $R_{DS(ON)}$ | 25m Ω |
| I_D | 28A |

Description

Advanced Power MOSFETs from APEC provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-252 package is widely preferred for all commercial-industrial surface mount applications and suited for low voltage applications such as DC/DC converters. The through-hole version (AP40T03GJ) are available for low-profile applications.



Absolute Maximum Ratings

| Symbol | Parameter | Rating | Units |
|-----------------------|--|------------|---------------|
| V_{DS} | Drain-Source Voltage | 30 | V |
| V_{GS} | Gate-Source Voltage | +25 | V |
| $I_D@T_C=25^\circ C$ | Continuous Drain Current, V_{GS} @ 10V | 28 | A |
| $I_D@T_C=100^\circ C$ | Continuous Drain Current, V_{GS} @ 10V | 24 | A |
| I_{DM} | Pulsed Drain Current ¹ | 95 | A |
| $P_D@T_C=25^\circ C$ | Total Power Dissipation | 31.25 | W |
| | Linear Derating Factor | 0.25 | W/ $^\circ C$ |
| T_{STG} | Storage Temperature Range | -55 to 150 | $^\circ C$ |
| T_J | Operating Junction Temperature Range | -55 to 150 | $^\circ C$ |

Thermal Data

| Symbol | Parameter | Value | Units |
|--------|---|-------|--------------|
| Rthj-c | Maximum Thermal Resistance, Junction-case | 4 | $^\circ C/W$ |
| Rthj-a | Maximum Thermal Resistance, Junction-ambient (PCB mount) ³ | 62.5 | $^\circ C/W$ |
| Rthj-a | Maximum Thermal Resistance, Junction-ambient | 110 | $^\circ C/W$ |



AP40T03GH/J

Electrical Characteristics @T_j=25°C (unless otherwise specified)

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Units |
|-------------------------------------|--|--|------|-------|------|-------|
| BV _{DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V, I _D =250uA | 30 | - | - | V |
| ΔBV _{DSS} /ΔT _j | Breakdown Voltage Temperature Coefficient | Reference to 25°C, I _D =1mA | - | 0.032 | - | V/°C |
| R _{DS(ON)} | Static Drain-Source On-Resistance ² | V _{GS} =10V, I _D =18A | - | - | 25 | mΩ |
| | | V _{GS} =4.5V, I _D =14A | - | - | 45 | mΩ |
| V _{GS(th)} | Gate Threshold Voltage | V _{DS} =V _{GS} , I _D =250uA | 1 | - | 3 | V |
| g _{fs} | Forward Transconductance | V _{DS} =10V, I _D =18A | - | 15 | - | S |
| I _{DSS} | Drain-Source Leakage Current | V _{DS} =30V, V _{GS} =0V | - | - | 1 | uA |
| | Drain-Source Leakage Current (T _j =150°C) | V _{DS} =24V, V _{GS} =0V | - | - | 25 | uA |
| I _{GSS} | Gate-Source Leakage | V _{GS} = ±25V | - | - | ±100 | nA |
| Q _g | Total Gate Charge ² | I _D =18A | - | 8.8 | - | nC |
| Q _{gs} | Gate-Source Charge | V _{DS} =20V | - | 2.5 | - | nC |
| Q _{gd} | Gate-Drain ("Miller") Charge | V _{GS} =4.5V | - | 5.8 | - | nC |
| t _{d(on)} | Turn-on Delay Time ² | V _{DS} =15V | - | 6 | - | ns |
| t _r | Rise Time | I _D =18A | - | 62 | - | ns |
| t _{d(off)} | Turn-off Delay Time | R _G =3.3Ω, V _{GS} =10V | - | 16 | - | ns |
| t _f | Fall Time | R _D =0.83Ω | - | 4.4 | - | ns |
| C _{iss} | Input Capacitance | V _{GS} =0V | - | 655 | - | pF |
| C _{oss} | Output Capacitance | V _{DS} =25V | - | 145 | - | pF |
| C _{rss} | Reverse Transfer Capacitance | f=1.0MHz | - | 95 | - | pF |

Source-Drain Diode

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Units |
|-----------------|---|--|------|------|------|-------|
| I _S | Continuous Source Current (Body Diode) | V _D =V _G =0V, V _S =1.3V | - | - | 28 | A |
| I _{SM} | Pulsed Source Current (Body Diode) ¹ | | - | - | 95 | A |
| V _{SD} | Forward On Voltage ² | T _j =25°C, I _S =28A, V _{GS} =0V | - | - | 1.3 | V |

Notes:

1. Pulse width limited by Max. junction temperature.
2. Pulse test
3. Surface mounted on 1 in² copper pad of FR4 board

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

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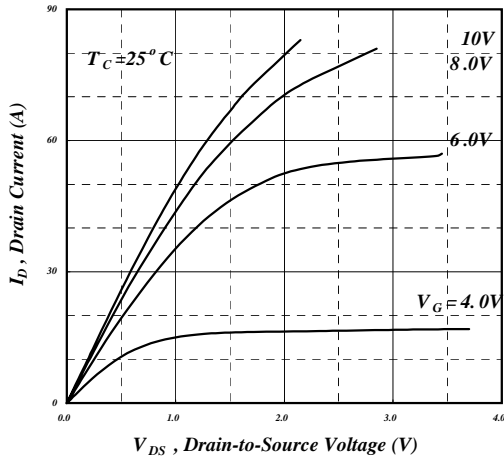


Fig 1. Typical Output Characteristics

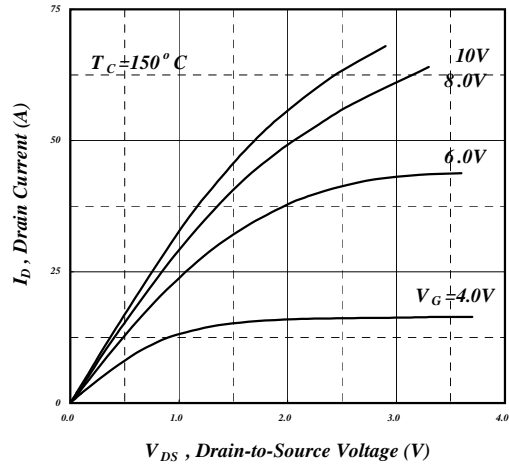


Fig 2. Typical Output Characteristics

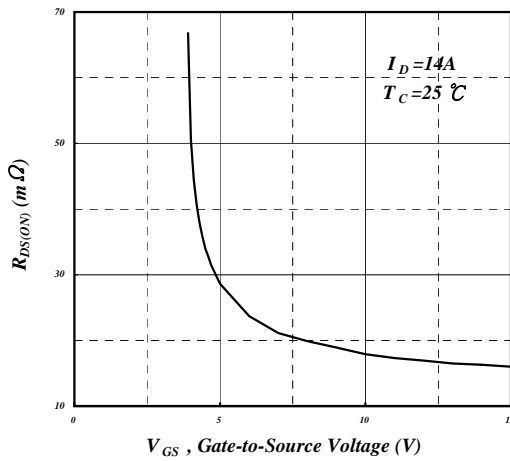


Fig 3. On-Resistance v.s. Gate Voltage

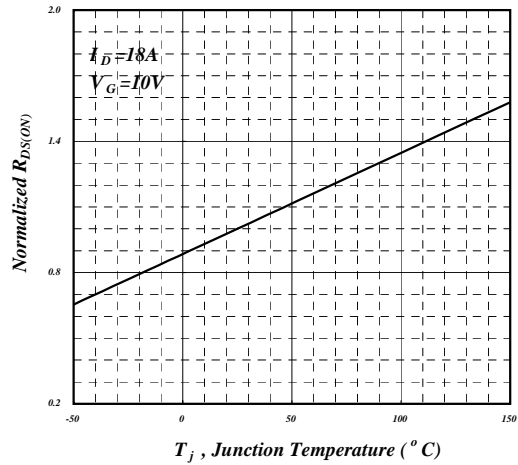


Fig 4. Normalized On-Resistance v.s. Junction Temperature

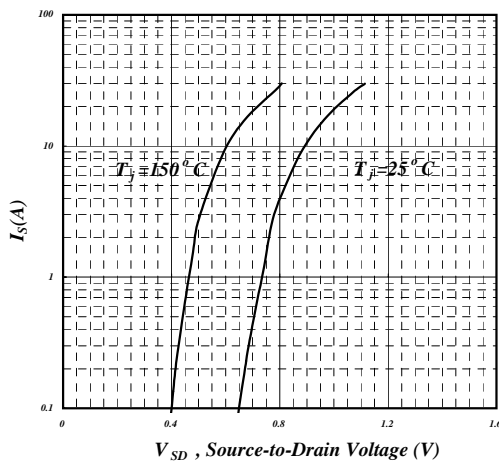


Fig 5. Forward Characteristic of Reverse Diode

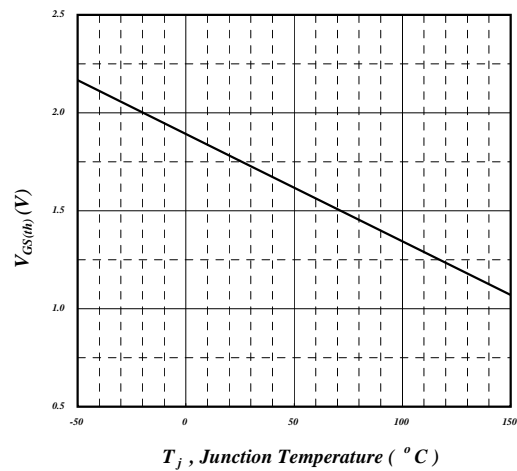


Fig 6. Gate Threshold Voltage v.s. Junction Temperature

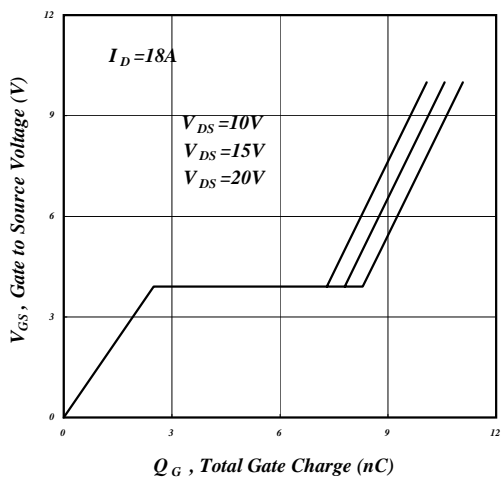


Fig 7. Gate Charge Characteristics

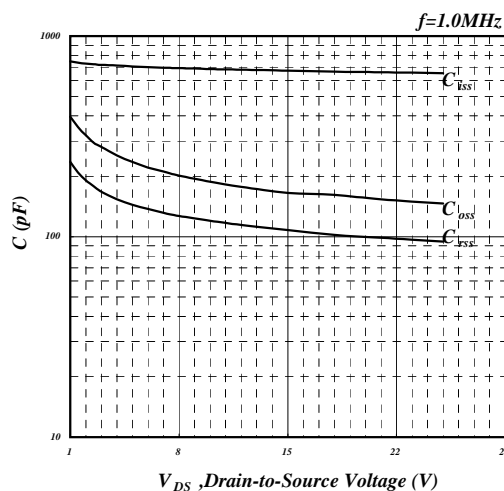


Fig 8. Typical Capacitance Characteristics

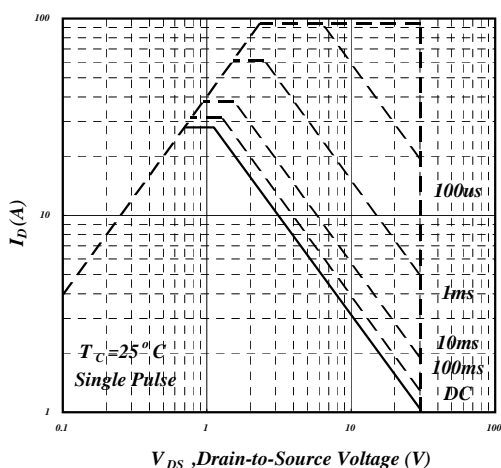


Fig 9. Maximum Safe Operating Area

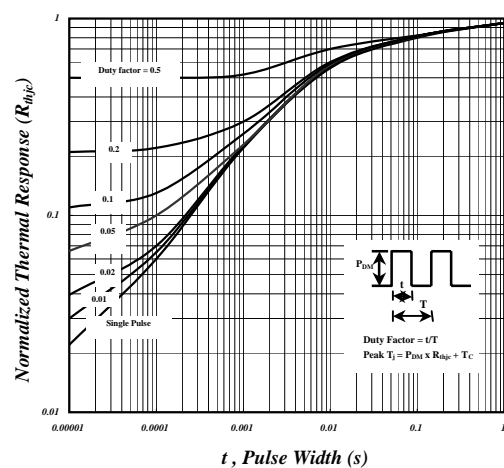


Fig 10. Effective Transient Thermal Impedance

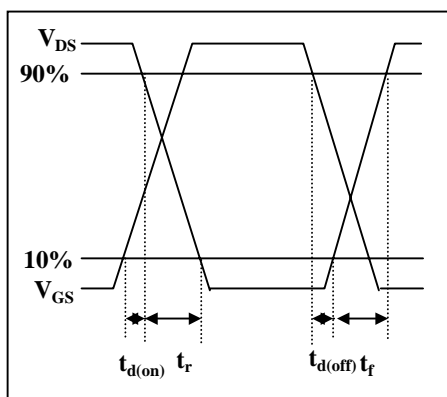


Fig 11. Switching Time Waveform

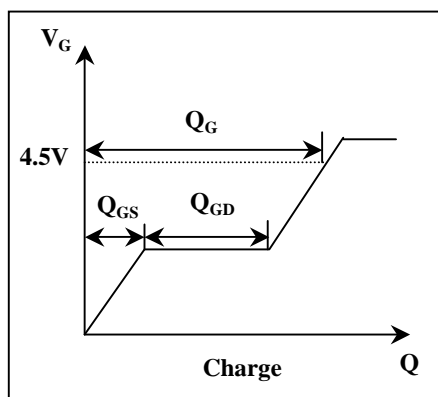
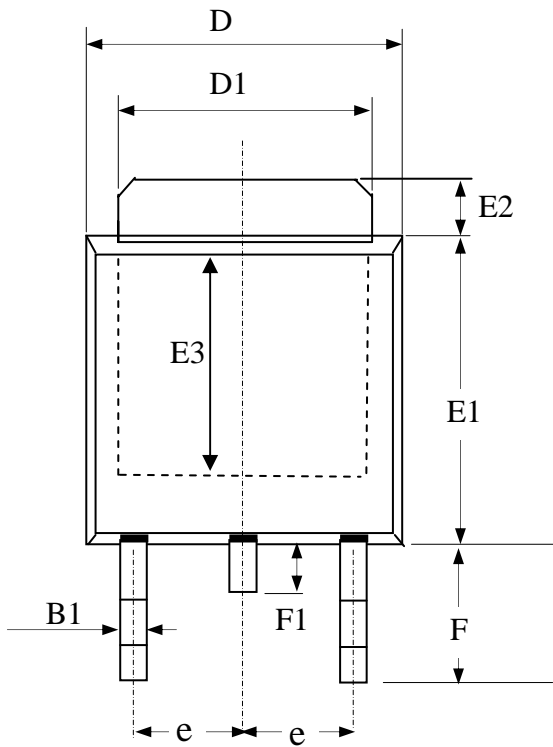


Fig 12. Gate Charge Waveform

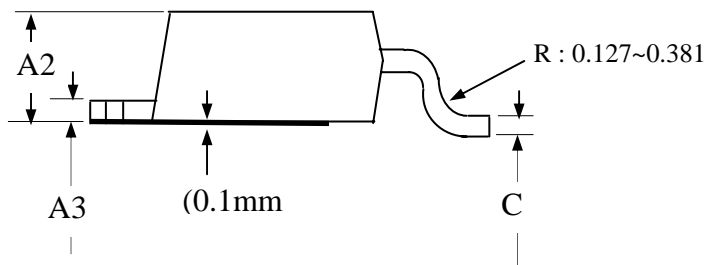


Package Outline : TO-252

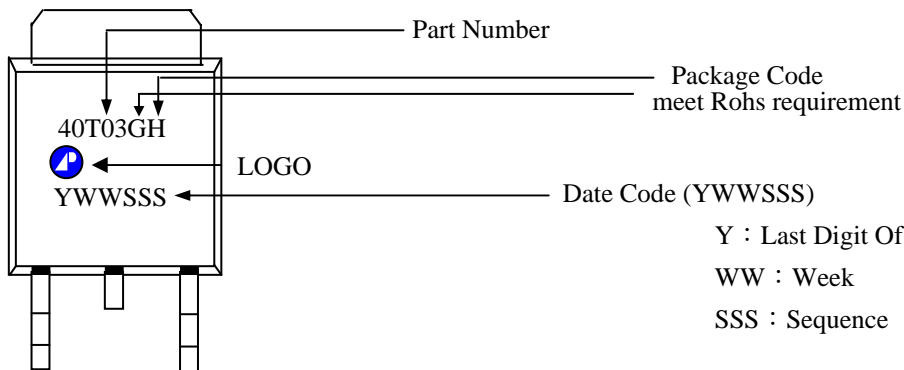


| SYMBOLS | Millimeters | | |
|---------|-------------|------|------|
| | MIN | NOM | MAX |
| A2 | 1.80 | 2.30 | 2.80 |
| A3 | 0.40 | 0.50 | 0.60 |
| B1 | 0.40 | 0.70 | 1.00 |
| D | 6.00 | 6.50 | 7.00 |
| D1 | 4.80 | 5.35 | 5.90 |
| E3 | 3.50 | 4.00 | 4.50 |
| F | 2.20 | 2.63 | 3.05 |
| F1 | 0.5 | 0.85 | 1.20 |
| E1 | 5.10 | 5.70 | 6.30 |
| E2 | 0.50 | 1.10 | 1.80 |
| e | -- | 2.30 | -- |
| C | 0.35 | 0.50 | 0.65 |

- 1.All Dimensions Are in Millimeters.
- 2.Dimension Does Not Include Mold Protrusions.



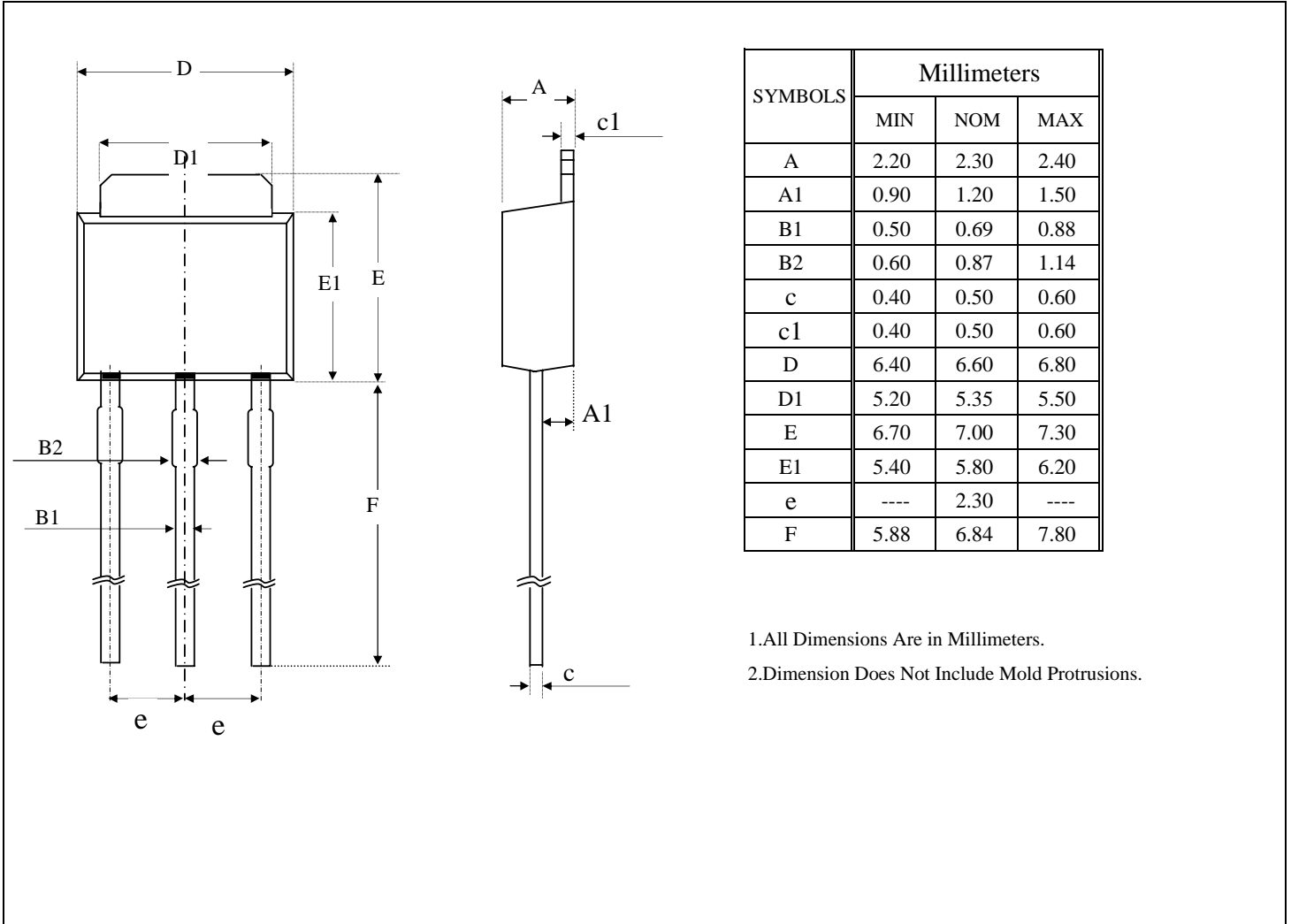
Part Marking Information & Packing : TO-252



Y : Last Digit Of The Year
 WW : Week
 SSS : Sequence



Package Outline : TO-251



Part Marking Information & Packing : TO-251

